



CBR-SMD RF COG, Ceramic, 9.2 pF, +/-0.25 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



General Information		
Series	CBR-SMD RF COG	
Style	SMD Chip	
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I	
Features	Ultra High Q, Low ESR, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	0.3 mg	
Notes	Solder Reflow Only.	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
Т	0.3mm +/-0.03mm
В	0.15mm +/-0.05mm

W	0.3mm +/-0.03mm	Voltage DC	25 VDC
Т	0.3mm +/-0.03mm	Dielectric Withstanding Voltage	62.5 VDC
В	0.15mm +/-0.05mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.171%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	15000	Insulation Resistance	10 GOhms

Chip Size	0201	Capacitance	9.2 pF
L	0.6mm +/-0.03mm	Tolerance	+/-0.25 pF
W	0.3mm +/-0.03mm	Voltage DC	25 VDC
Т	0.3mm +/-0.03mm	Dielectric Withstanding Voltage	62.5 VDC
В	0.15mm +/-0.05mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.171%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	15000	Insulation Resistance	10 GOhms
		Quality Factor	584

Specifications

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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